

CS8161

12 V, 5.0 V Low Dropout Dual Regulator with ENABLE

The CS8161 is a 12 V/5.0 V dual output linear regulator. The 12V $\pm 5.0\%$ output sources 400 mA and the 5.0 V $\pm 2.0\%$ output sources 200 mA.

The on board ENABLE function controls the regulator's two outputs. When the ENABLE pin is low, the regulator is placed in SLEEP mode. Both outputs are disabled and the regulator draws only 200 nA of quiescent current.

The primary output, V_{OUT1} is protected against overvoltage conditions. Both outputs are protected against short circuit and thermal runaway conditions.

The CS8161 is packaged in a 5 lead TO-220 with copper tab. The copper tab can be connected to a heat sink if necessary.

Features

- Two Regulated Outputs
 - 12 V $\pm 5.0\%$; 400 mA
 - 5.0 V $\pm 2.0\%$; 200 mA
- Very Low SLEEP Mode Current Drain 200 nA
- Fault Protection
 - Reverse Battery (-15 V)
 - 74 V Load Dump
 - -100 V Reverse Transient
 - Short Circuit
 - Thermal Shutdown

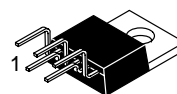


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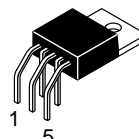
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TO-220
FIVE LEAD
T SUFFIX
CASE 314D

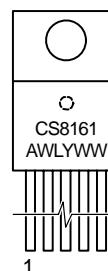


TO-220
FIVE LEAD
TVA SUFFIX
CASE 314K



TO-220
FIVE LEAD
THA SUFFIX
CASE 314A

PIN CONNECTIONS AND MARKING DIAGRAM



Tab = GND
Pin 1. V_{IN}
2. V_{OUT1}
3. GND
4. ENABLE
5. V_{OUT2}

A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week

ORDERING INFORMATION*

Device	Package	Shipping
CS8161YT5	TO-220** STRAIGHT	50 Units/Rail
CS8161YTVA5	TO-220** VERTICAL	50 Units/Rail
CS8161YTHA5	TO-220** HORIZONTAL	50 Units/Rail

*Consult your local sales representative for SO-16L package option.

**Five lead.

CS8161

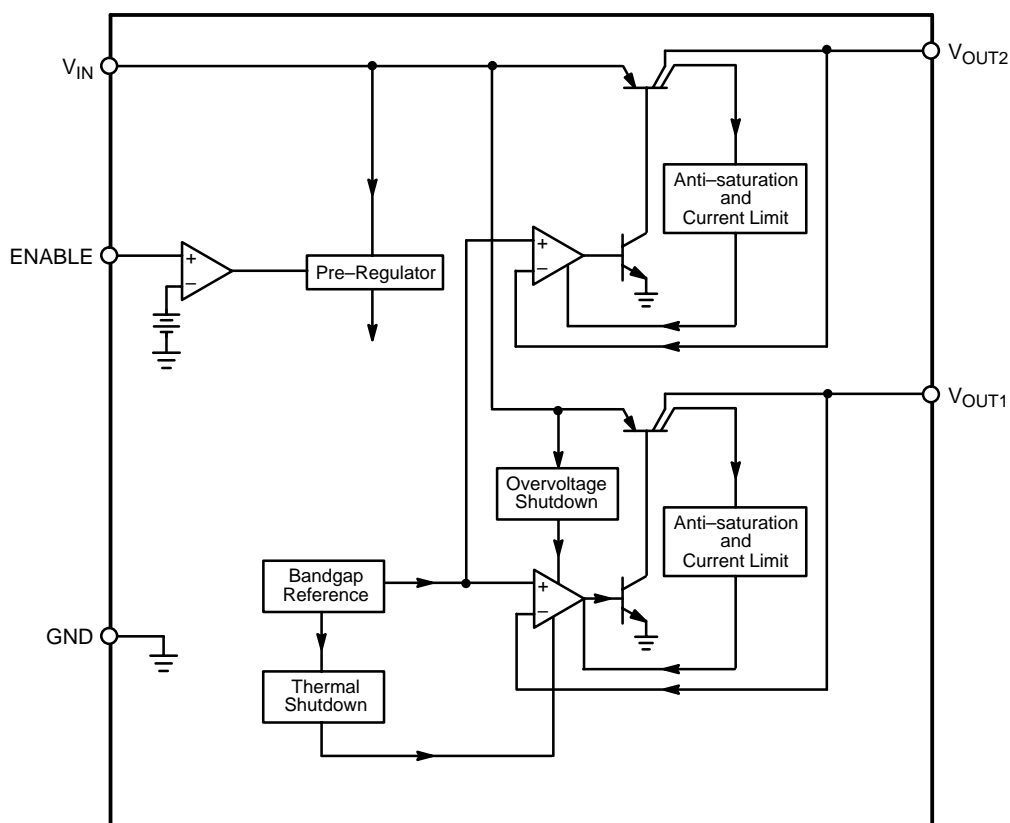


Figure 1. Block Diagram

ABSOLUTE MAXIMUM RATINGS*

Rating	Value	Unit
Input Voltage:	Operating Range Overvoltage Protection	–15 to 26 74 V V
Internal Power Dissipation	Internally Limited	–
Junction Temperature Range	–40 to +150	°C
Storage Temperature Range	–65 to +150	°C
Lead Temperature Soldering:	Wave Solder (through hole styles only) (Note 1.) Reflow (SMD styles only) (Note 2.)	260 peak 230 peak °C °C
ESD (Human Body Model)	2.0	kV

1. 10 second maximum.

2. 60 second maximum above 183°C

*The maximum package power dissipation must be observed.

CS8161

ELECTRICAL CHARACTERISTICS for V_{OUT} : ($6.0\text{ V} \leq V_{IN} \leq 26\text{ V}$; $I_{OUT1} = 5.0\text{ mA}$; $I_{OUT2} = 5.0\text{ mA}$;
 $-40^{\circ}\text{C} \leq T_J \leq +150^{\circ}\text{C}$; $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$; unless otherwise specified.)

Characteristic	Test Conditions	Min	Typ	Max	Unit
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Primary Output Stage (V_{OUT1})

Output Voltage, V_{OUT1}	$13\text{ V} \leq V_{IN} \leq 26\text{ V}$, $I_{OUT1} \leq 400\text{ mA}$	11.4	12.0	12.6	V
Dropout Voltage	$I_{OUT1} = 400\text{ mA}$	–	0.35	0.6	V
Line Regulation	$13\text{ V} \leq V_{IN} \leq 20\text{ V}$, $5.0\text{ mA} \leq I_{OUT} < 400\text{ mA}$	–	–	80	mV
Load Regulation	$5.0\text{ mA} \leq I_{OUT1} \leq 400\text{ mA}$, $V_{IN} = 14\text{ V}$	–	–	80	mV
Quiescent Current	$I_{OUT1} \leq 100\text{ mA}$, No Load on V_{OUT2} $I_{OUT1} \leq 400\text{ mA}$, No Load on V_{OUT2}	– –	8.0 50	12 75	mA mA
Ripple Rejection	$f = 120\text{ Hz}$, $I_{OUT} = 300\text{ }\mu\text{A}$, $V_{IN} = 15.0\text{ V}_{DC}$, 2.0 V_{RMS}	42	–	–	dB
Current Limit	–	0.40	–	1.0	A
Reverse Polarity Input Voltage, DC	$V_{OUT1} \geq -0.6\text{ V}$, $10\text{ }\Omega$ Load	–	–30	–18	V
Reverse Polarity Input Voltage, Transient	1.0% Duty Cycle, $t = 100\text{ ms}$, $V_{OUT} \geq -6.0\text{ V}$, $10\text{ }\Omega$ Load	–	–80	–50	V
Overvoltage Shutdown	–	28	34	45	V
Short Circuit Current	–	–	–	700	mA

Secondary Output (V_{OUT2})

Output Voltage, (V_{OUT2})	$6.0\text{ V} \leq V_{IN} \leq 26\text{ V}$, $I_{OUT2} \leq 200\text{ mA}$	4.90	–	5.10	V
Dropout Voltage	$I_{OUT2} \leq 200\text{ mA}$	–	0.35	0.60	V
Line Regulation	$6.0\text{ V} \leq V_{IN} \leq 26\text{ V}$, $1.0\text{ mA} \leq I_{OUT} \leq 200\text{ mA}$	–	–	50	mV
Load Regulation	$1.0\text{ mA} \leq I_{OUT2} \leq 200\text{ mA}$; $V_{IN} = 14\text{ V}$	–	–	50	mV
Quiescent Current	$I_{OUT2} = 50\text{ mA}$ $I_{OUT2} = 200\text{ mA}$	– –	5.0 20	10 35	mA mA
Ripple Rejection	$f = 120\text{ Hz}$; $I_{OUT} = 10\text{ mA}$, $V_{IN} = 15\text{ V}$, 2.0 V_{RMS}	42	–	–	dB
Current Limit	–	200	–	600	mA
Short Circuit Current	–	–	–	400	mA

ENABLE Function (ENABLE)

Input ENABLE Threshold	V_{OUT1} Off V_{OUT1} On	– 2.00	1.30 1.30	0.80 –	V V
Input ENABLE Current	$V_{ENABLE} = 5.5\text{ V}$ $V_{ENABLE} < 0.8\text{ V}$	80 –10	– –	500 10	μA μA

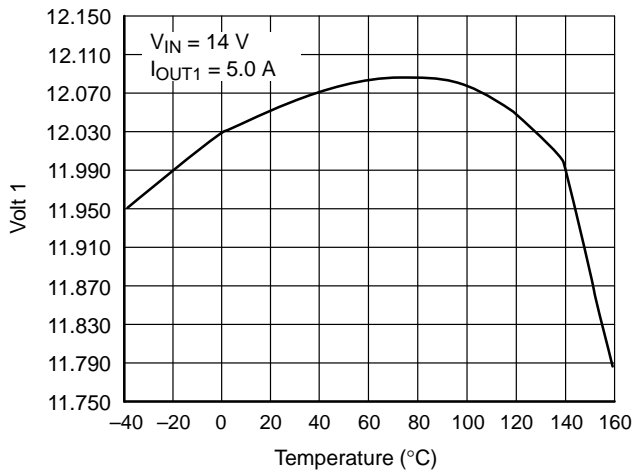
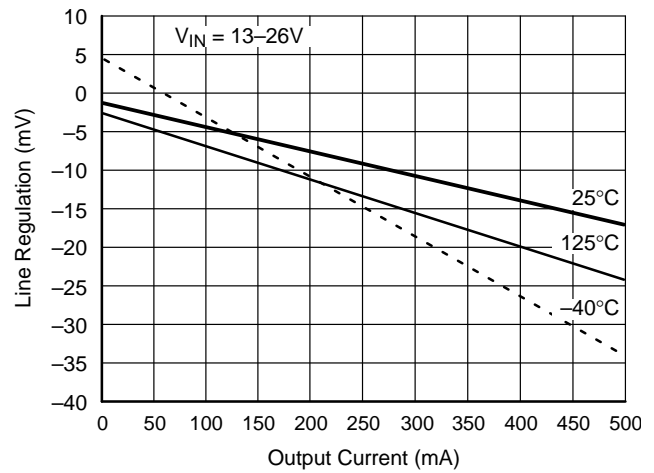
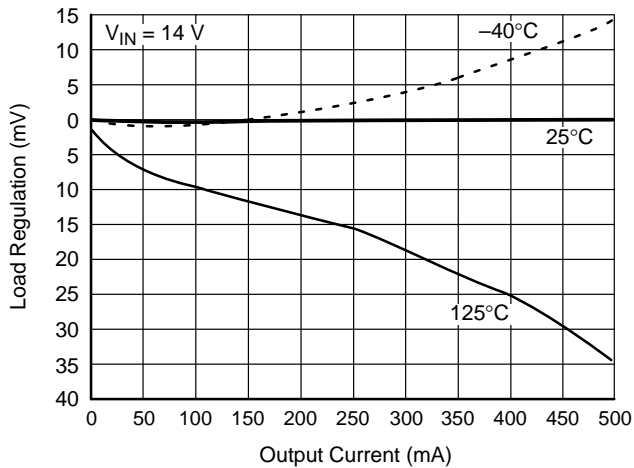
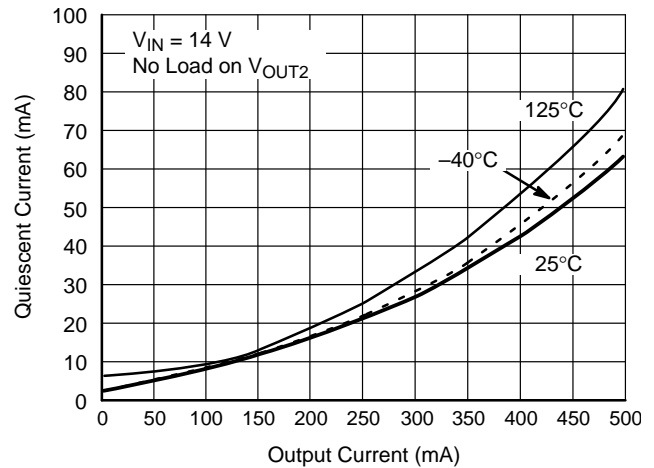
Other Features

Sleep Mode	$V_{ENABLE} < 0.4\text{ V}$	–	0.2	50	μA
Thermal Shutdown	–	150	–	210	$^{\circ}\text{C}$
Quiescent Current in Dropout	$I_{OUT1} = 100\text{ mA}$, $I_{OUT2} = 50\text{ mA}$	–	–	60	mA

PACKAGE PIN DESCRIPTION

PACKAGE LEAD #	LEAD SYMBOL	FUNCTION
5 Lead TO-220		
1	V_{IN}	Supply voltage, usually direct from battery.
2	V_{OUT1}	Regulated output 12 V, 400 mA (typ).
3	GND	Ground connection.
4	ENABLE	CMOS compatible input lead; switches outputs on and off. When ENABLE is high V_{OUT1} and V_{OUT2} are active.
5	V_{OUT2}	Regulated output 5.0 V, 200 mA (typ).

TYPICAL PERFORMANCE CHARACTERISTICS

Figure 2. Output Voltage vs. Temperature for V_{OUT1} Figure 3. Line Regulation vs. Output Current for V_{OUT1} Figure 4. Load Regulation vs. Output Current for V_{OUT1} Figure 5. Quiescent Current vs. Output Current for V_{OUT1}

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

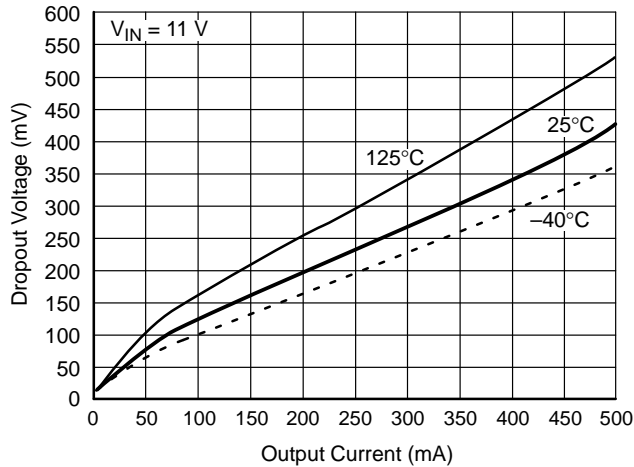


Figure 6. Dropout Voltage vs. Output Voltage for V_{OUT1}

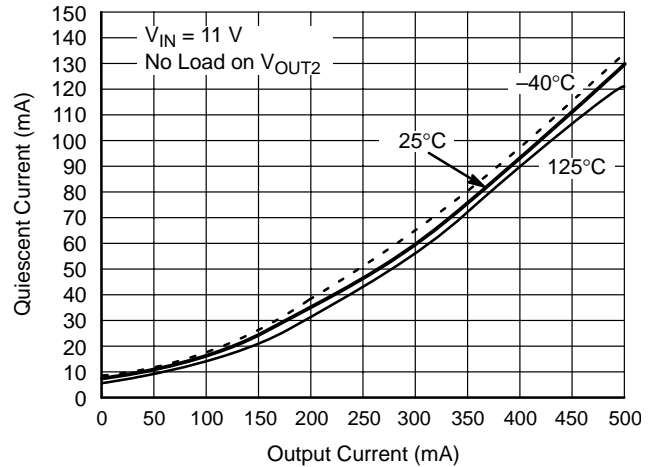


Figure 7. Quiescent Current vs. Output Current @ Dropout for V_{OUT1}

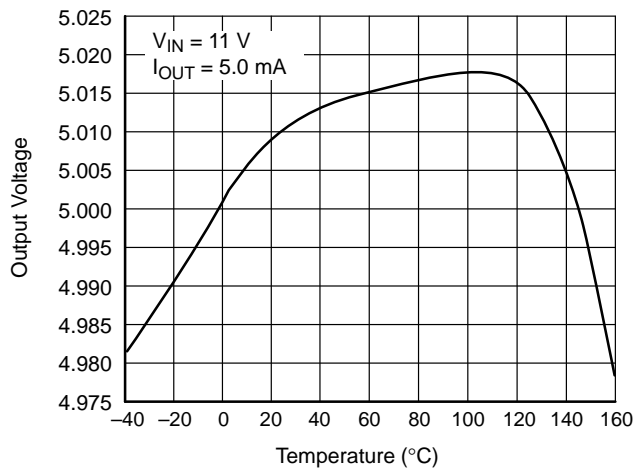


Figure 8. Output Voltage vs. Temperature for V_{OUT2}

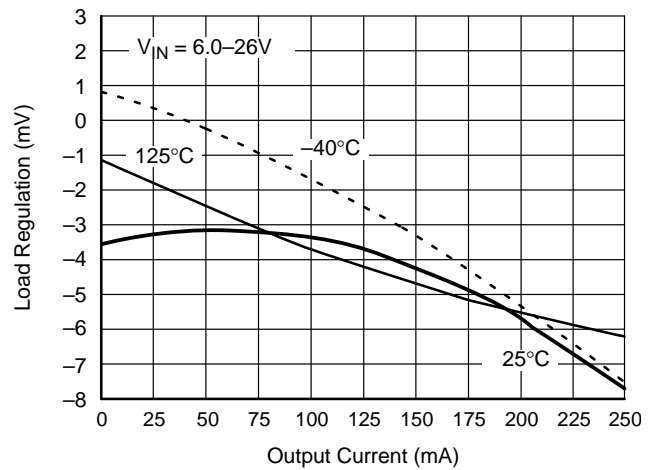


Figure 9. Line Regulation vs. Output Current for V_{OUT2}

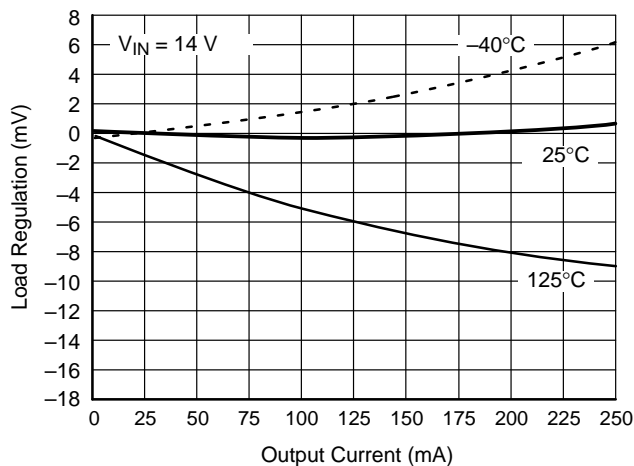


Figure 10. Load Regulation vs. Output Current for V_{OUT2}

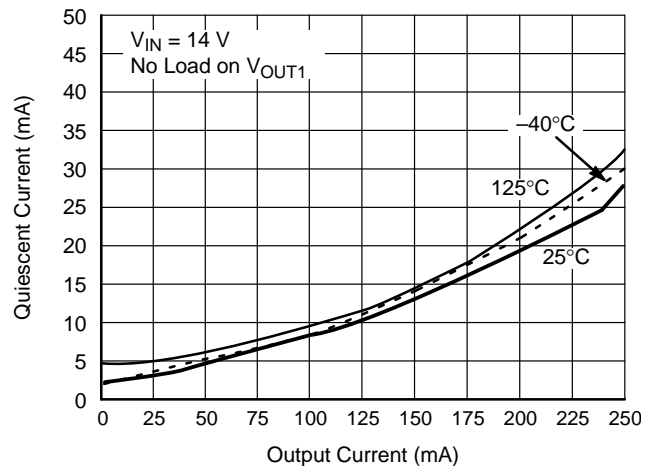


Figure 11. Quiescent Current vs. Output Current for V_{OUT2}

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

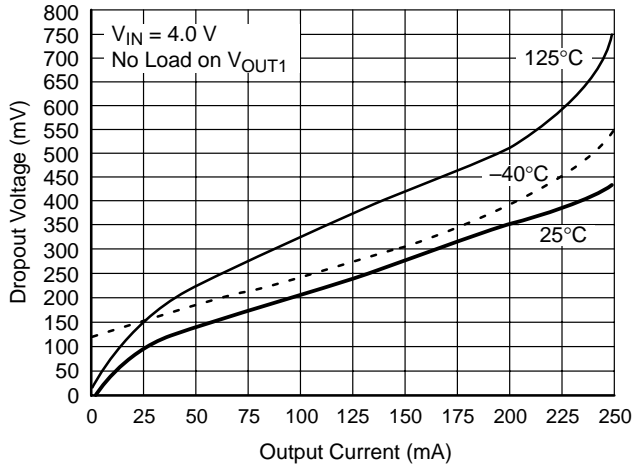


Figure 12. Dropout Voltage vs. Output Current for V_{OUT2}

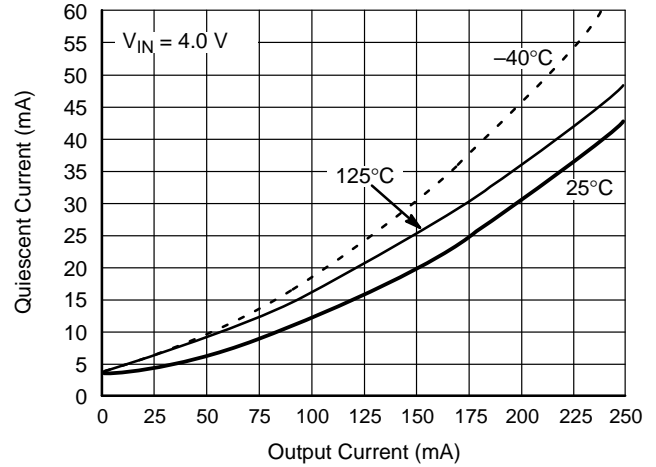


Figure 13. Quiescent Current vs. Output Current @ Dropout for V_{OUT2}

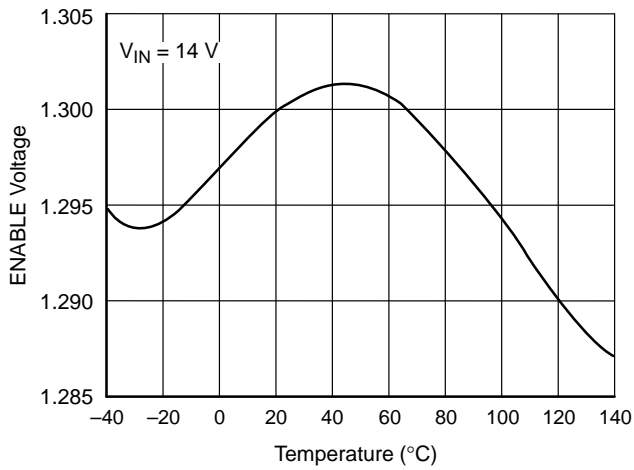


Figure 14. Enable Threshold Voltage vs. Temperature

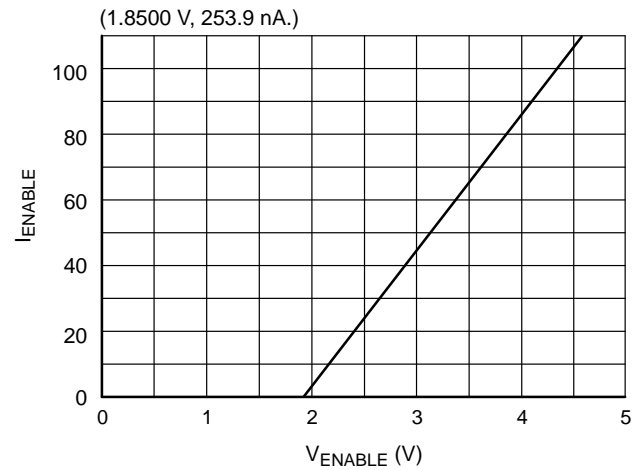


Figure 15. ENABLE Current vs. ENABLE Voltage

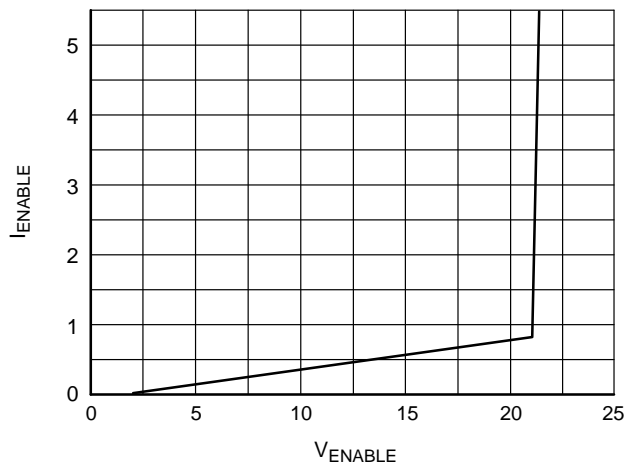


Figure 16. 12 mA ENABLE Current vs. ENABLE Voltage

DEFINITION OF TERMS

Dropout Voltage – The input–output voltage differential at which the circuit ceases to regulate against further reduction in input voltage. Measured when the output voltage has dropped 100 mV from the nominal value obtained at 14 V input, dropout voltage is dependent upon load current and junction temperature.

Input Voltage – The DC voltage applied to the input terminals with respect to ground.

Input Output Differential – The voltage difference between the unregulated input voltage and the regulated output voltage for which the regulator will operate.

Line Regulation – The change in output voltage for a change in the input voltage. The measurement is made under conditions of low dissipation or by using pulse techniques such that the average chip temperature is not significantly affected.

Load Regulation – The change in output voltage for a change in load current at constant chip temperature.

Long Term Stability – Output voltage stability under accelerated life–test conditions after 1000 hours with maximum rated voltage and junction temperature.

Output Noise Voltage – The rms AC voltage at the output, with constant load and no input ripple, measured over a specified frequency range.

Quiescent Current – The part of the positive input current that does not contribute to the positive load current, i.e., the regulator ground lead current.

Ripple Rejection – The ratio of the peak–to–peak input ripple voltage to the peak–to–peak output ripple voltage.

Temperature Stability of V_{OUT} – The percentage change in output voltage for a thermal variation from room temperature to either temperature extreme.

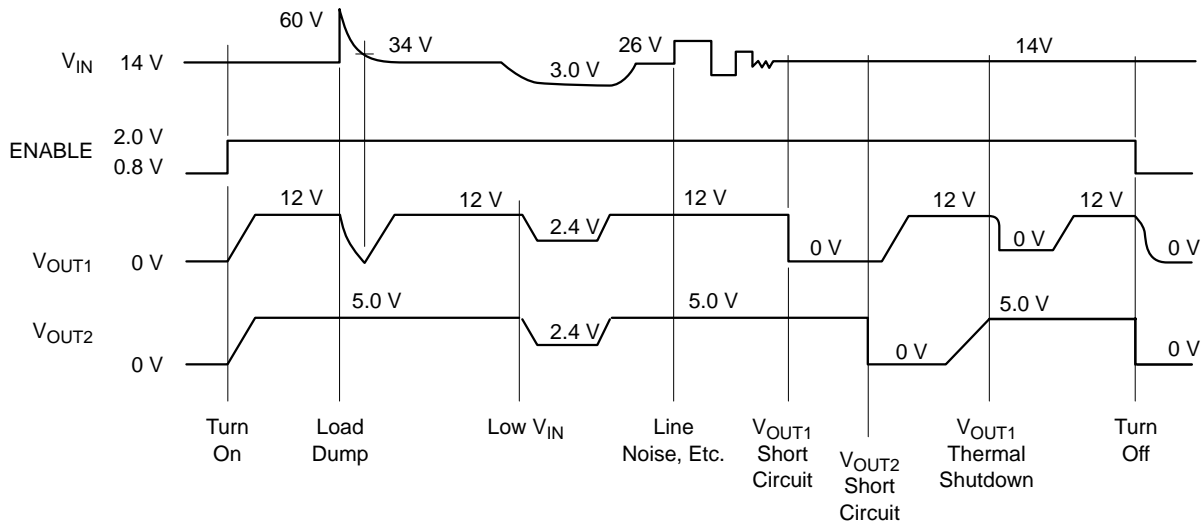
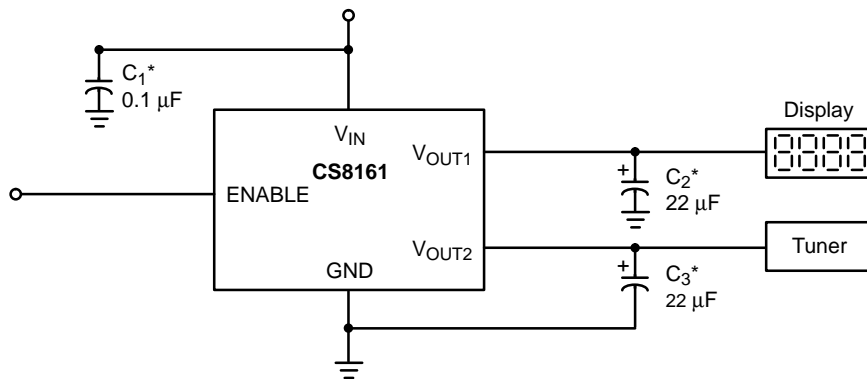


Figure 17. Typical Circuit Waveform

APPLICATION DIAGRAM



* C_1 required if regulator is located far from power supply filter.

** C_2 , C_3 required for stability, value may be increased. Capacitor must operate at minimum temperature expected.

Figure 18. Application Diagram

APPLICATION NOTES

Since both outputs are controlled by the same ENABLE, the CS8161 is ideal for applications where a sleep mode is required. Using the CS8161, a section of circuitry such as a display and nonessential 5.0 V circuits can be shut down under microprocessor control to conserve energy.

The example in the Applications Diagram (Figure 18) shows an automotive radio application where the display is powered by the 12 V on V_{OUT1} and the Tuner IC is powered by the 5.0 V on V_{OUT2}. Neither output is required unless both the ignition and the Radio On/Off switch are on.

Stability Considerations

The output or compensation capacitor (Application diagram C₂ and C₃) helps determine three main characteristics of a linear regulator: start-up delay, load transient response and loop stability.

The capacitor value and type should be based on cost, availability, size and temperature constraints. A tantalum or aluminum electrolytic capacitor is best, since a film or ceramic capacitor with almost zero ESR can cause instability. The aluminum electrolytic capacitor is the cheapest solution, but, if the circuit operates at low temperatures (–25°C to –40°C), both the value and ESR of the capacitor will vary considerably. The capacitor manufacturers data sheet usually provides this information.

The values for the output capacitors C₂ and C₃ shown in the test and applications circuit should work for most applications, however it is not necessarily the best solution.

To determine acceptable values for C₂ and C₃ for a particular application, start with tantalum capacitors of the recommended value on each output and work towards less expensive alternative parts for each output in turn.

Step 1: Place the completed circuit with a tantalum capacitor of the recommended value in an environmental chamber at the lowest specified operating temperature and monitor the outputs on the oscilloscope. A decade box connected in series with the capacitor C₂ will simulate the higher ESR of an aluminum capacitor. (Leave the decade box outside the chamber, the small resistance added by the longer leads is negligible)

Step 2: With the input voltage at its maximum value, increase the load current slowly from zero to full load while observing the output for any oscillations. If no oscillations are observed, the capacitor is large enough to ensure a stable design under steady state conditions.

Step 3: Increase the ESR of the capacitor from zero using the decade box and vary the load current until oscillations appear. Record the values of load current and ESR that cause the greatest oscillation. This represents the worst case load conditions for the regulator at low temperature.

Step 4: Maintain the worst case load conditions set in step 3 and vary the input voltage until the oscillations increase. This point represents the worst case input voltage conditions.

Step 5: If the capacitor C₂ is adequate, repeat steps 3 and 4 with the next smaller valued capacitor. (A smaller capacitor will usually cost less and occupy less board space.) If the capacitor oscillates within the range of expected operating conditions, repeat steps 3 and 4 with the next larger standard capacitor value.

Step 6: Test the load transient response by switching in various loads at several frequencies to simulate its real work environment. Vary the ESR to reduce ringing.

Step 7: Raise the temperature to the highest specified operating temperature. Vary the load current as instructed in step 5 to test for any oscillations.

Once the minimum capacitor value with the maximum ESR is found, a safety factor should be added to allow for the tolerance of the capacitor and any variations in regulator performance. Most good quality aluminum electrolytic capacitors have a tolerance of ±20% so the minimum value found should be increased by at least 50% to allow for this tolerance plus the variation which will occur at low temperatures. The ESR of the capacitors should be less than 50% of the maximum allowable ESR found in step 3 above. Once the value for C₂ is determined, repeat the steps to determine the appropriate value for C₃.

Calculating Power Dissipation in a Dual Output Linear Regulator

The maximum power dissipation for a dual output regulator (Figure 19) is

$$P_{D(max)} = (V_{IN(max)} - V_{OUT1(min)})I_{OUT1(max)} + (V_{IN(max)} - V_{OUT2(min)})I_{OUT2(max)} + V_{IN(max)}I_Q \quad (1)$$

where:

V_{IN(max)} is the maximum input voltage,

V_{OUT1(min)} is the minimum output voltage from V_{OUT1},

V_{OUT2(min)} is the minimum output voltage from V_{OUT2},

I_{OUT1(max)} is the maximum output current, for the application,

I_{OUT2(max)} is the maximum output current, for the application, and

I_Q is the quiescent current the regulator consumes at I_{OUT(max)}.

Once the value of P_{D(max)} is known, the maximum permissible value of R_{ΘJA} can be calculated:

$$R_{\Theta JA} = \frac{150^{\circ}\text{C} - T_A}{P_D} \quad (2)$$

The value of R_{ΘJA} can be compared with those in the package section of the data sheet. Those packages with R_{ΘJA}'s less than the calculated value in equation 2 will keep the die temperature below 150°C.

In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heatsink will be required.

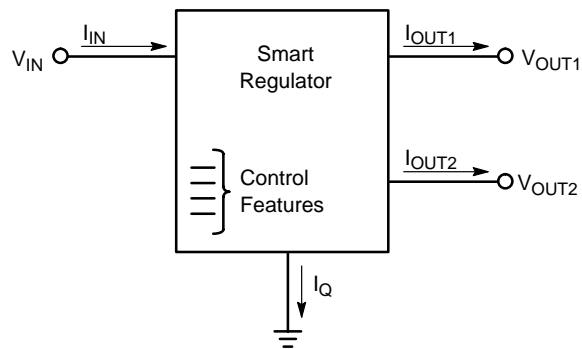


Figure 19. Dual Output Regulator With Key Performance Parameters Labeled.

Heat Sinks

A heat sink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of $R_{\theta JA}$:

$$R_{\theta JA} = R_{\theta JC} + R_{\theta CS} + R_{\theta SA} \quad (3)$$

where:

$R_{\theta JC}$ = the junction-to-case thermal resistance,

$R_{\theta CS}$ = the case-to-heatsink thermal resistance, and

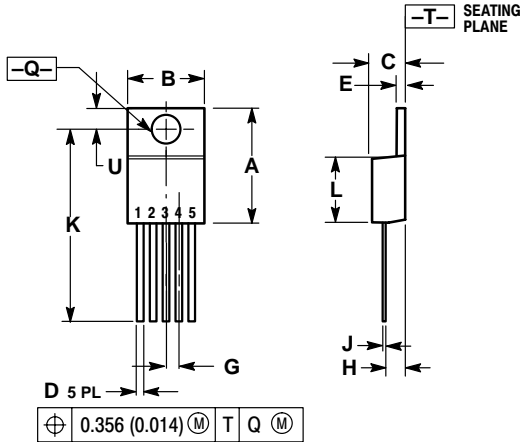
$R_{\theta SA}$ = the heatsink-to-ambient thermal resistance.

$R_{\theta JC}$ appears in the package section of the data sheet. Like $R_{\theta JA}$, it too is a function of package type. $R_{\theta CS}$ and $R_{\theta SA}$ are functions of the package type, heatsink and the interface between them. These values appear in heat sink data sheets of heat sink manufacturers.

CS8161

PACKAGE DIMENSIONS

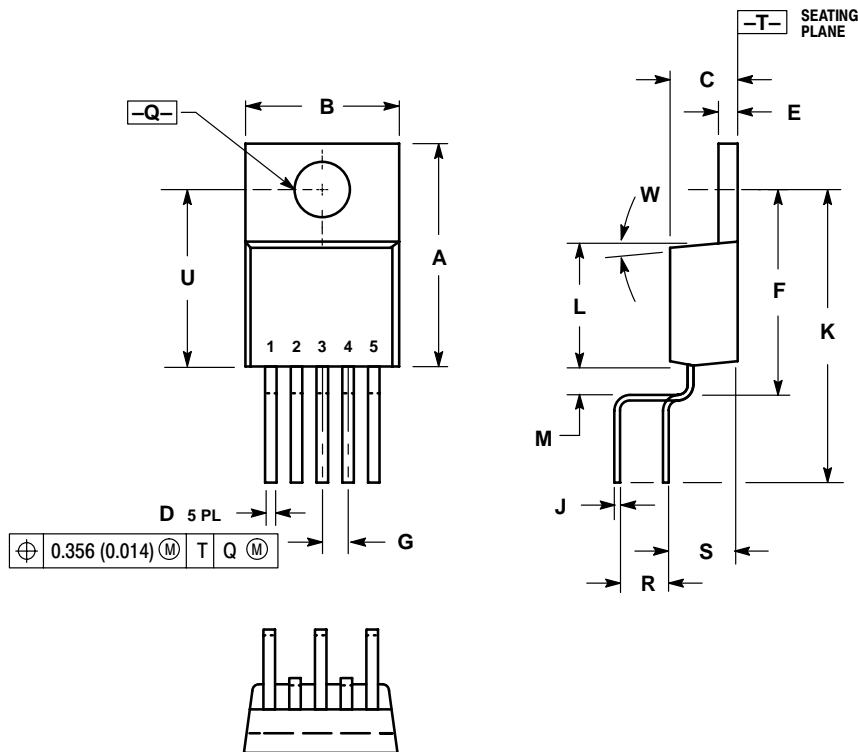
TO-220
FIVE LEAD
T SUFFIX
CASE 314D-04
ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
G	0.067 BSC		1.702 BSC	
H	0.087	0.112	2.210	2.845
J	0.015	0.025	0.381	0.635
K	0.990	1.045	25.146	26.543
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
U	0.105	0.117	2.667	2.972

TO-220
FIVE LEAD
TVA SUFFIX
CASE 314K-01
ISSUE O

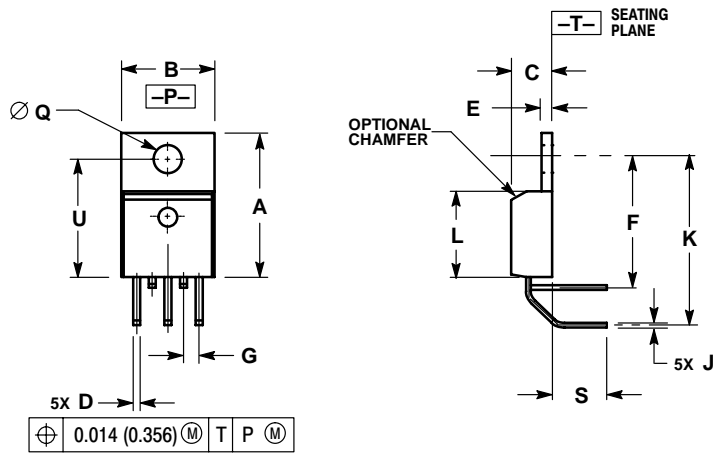


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DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.560	0.590	14.22	14.99
B	0.385	0.415	9.78	10.54
C	0.160	0.190	4.06	4.83
D	0.027	0.037	0.69	0.94
E	0.045	0.055	1.14	1.40
F	0.530	0.545	13.46	13.84
G	0.067 BSC		1.70 BSC	
J	0.014	0.022	0.36	0.56
K	0.785	0.800	19.94	20.32
L	0.321	0.337	8.15	8.56
M	0.063	0.078	1.60	1.98
Q	0.146	0.156	3.71	3.96
R	0.271	0.321	6.88	8.15
S	0.146	0.196	3.71	4.98
U	0.460	0.475	11.68	12.07
W	5°		5°	

CS8161

TO-220 FIVE LEAD THA SUFFIX CASE 314A-03 ISSUE E




NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
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	MIN	MAX	MIN	MAX
A	0.572	0.613	14.529	15.570
B	0.390	0.415	9.906	10.541
C	0.170	0.180	4.318	4.572
D	0.025	0.038	0.635	0.965
E	0.048	0.055	1.219	1.397
F	0.570	0.585	14.478	14.859
G	0.067 BSC		1.702 BSC	
J	0.015	0.025	0.381	0.635
K	0.730	0.745	18.542	18.923
L	0.320	0.365	8.128	9.271
Q	0.140	0.153	3.556	3.886
S	0.210	0.260	5.334	6.604
U	0.468	0.505	11.888	12.827

PACKAGE THERMAL DATA

Parameter		TO-220 FIVE LEAD	Unit
R _{θJC}	Typical	2.0	°C/W
R _{θJA}	Typical	50	°C/W

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